Additional assembly site

PRODUCT / PROCESS CHANGE NOTIFICATION Generic Copy

PCN#2303003 • DATE: 28th March, 2023

PCN Subject: Additional Assembly Site for Package SOT-23

• PCN Change Category:

Material
Process
Datasheet/Specification
Reliability

)

Description of Change Purpose or Reason:

Others (

This PCN is being issued to announce the qualification of PANJIT Semiconductor (Xuzhou) Co., Ltd (located in Jiangsu Province, China) as an alternate assembly and test site for SOT-23 selected products. The products that will be manufactured from this new assembly/test site are form, fit, and function compatible with the current qualified manufacturing sites. The qualification incorporates new bill of material (BOM) sets including the utilization of High-Density Leadframe with Alloy material, the change of wire type and wire diameter. For more detail, please check below change information.

We recommend that you acknowledge receipt of this notification within 30 days of this PCN date. If you require samples for further evaluation, please feel free to contact your local sales representative and make a request. We are always pleased to serve you at any time.

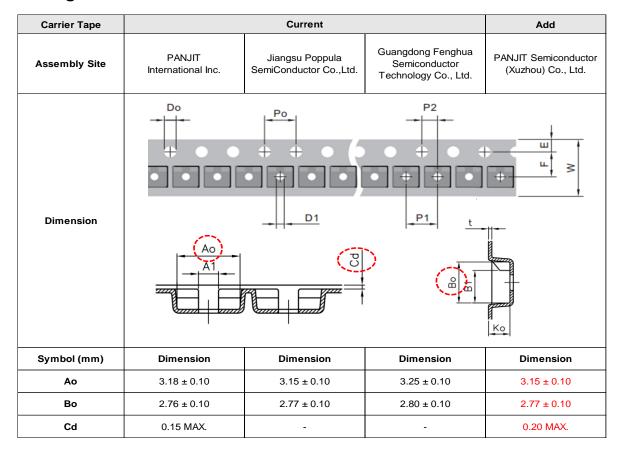
• Change Information:

Comparison		Table 1				
Assembly Site		Current			Add	
		PANJIT International Inc.	Jiangsu Poppula SemiConductor Co.,Ltd.	Guangdong Fenghua Semiconductor Technology Co., Ltd.	PANJIT Semiconducto (Xuzhou) Co., Ltd.	
	Location		Kaohsiung, Taiwan	Jiangsu, China	Guangdong, China	Xuzhou, China
		Supplier	Phenitec Semiconductor Corp.	Phenitec Semiconductor Corp.	Phenitec Semiconductor Corp.	Yangzhou Genesis Microelectronics Co., L
		Diameter (inch)	5"	5"	5"	5"
	Wafer	Die Size(um)	BAV99: 260 X 260 BAV70: 260 X 260 MMBD7000: 280 X 280	BAV99: 260 X 260 BAV70: 260 X 260 MMBD7000: 280 X 280	BAV99: 260 X 260 BAV70: 260 X 260 MMBD7000: 280 X 280	BAV99: 260 X 260 BAV70: 260 X 260 MMBD7000: 260 X 26
		Thickness (um)	230 ± 15	230 ± 15	230 ± 15	165 ± 15
	Lead Frame	Material	Alloy 42	Copper	Copper	Alloy 42
	Wire	Material / Diameter (mil)	Cu/1.0	Cu/1.0	Cu/1.0	Cu/0.8
	Epoxy Molding Compound	Product Name	ELER-8-500C	EME-E500DJ ELER-8-500C	EK-3600KH	GR640HV-L1 B18
Material	Carrier Tape	Material	Polycarbonate (PC)	Polycarbonate (PC) + Acrylonitrile Butadiene Styrene (ABS) + Polycarbonate (PC)	Polycarbonate (PC) + Polystyrene (PS)	Polystyrene (PS)
	Ending Tape	Material	Polyester	Paper	Paper	Paper
		Color	Black	White	Cream	Yellow
	Blue Anti-Static Plastic Reel					
Method	Process	De-Flash	Electrolytic De-flash	Chemical De-flash	Chemical De-flash	Chemical De-flash
Form	Marking	Format	·JAb	JAG	·JAA	Add bar "." for new assembly site

• Change Information:

Comparison			Table 2		
			Current	Add	
Assembly Site			PANJIT International Inc.	PANJIT Semiconducto (Xuzhou) Co., Ltd.	
	Location		Kaohsiung, Taiwan	Xuzhou, China	
		Supplier	Phenitec Semiconductor Corp.	Yangzhou Genesis Microelectronics Co., L	
		Diameter (inch)	5"	5"	
	Wafer	Die Size(um)	MMBT3904: 250 X 270 MMBT3906: 280 X 280 MMBT2907A: 490 X 490	MMBT3904: 260 X 260 MMBT3906: 260 X 260 MMBT2907A: 460 X 460	
		Thickness (um)	230 ± 20	165 ± 15	
	Lead Frame	Material	Alloy 42	Alloy 42	
	Wire	Material / Diameter (mil)	Ag / 1.0	Cu/0.8	
Material	Epoxy Molding Compound	Product Name	ELER-8-500C	GR640HV-L1 B18	
	Carrier Tape	Material	Polycarbonate (PC)	Polystyrene (PS)	
	Ending Tape	Material	Polyester	Paper	
	Ending Tape	Color	Black	Yellow	
	Blue Anti-Stati	c Plastic Reel			
Method	Process	De-Flash	Electrolytic De-flash	Chemical De-flash	
Form	Form Marking Format		·S2A5	S2A &	

• Change Information:



• Verification /Qualification Data:

The electrical characterization and high reliability testing have been completed on representative part numbers to ensure there is no change to device functionality or electrical specifications in the datasheet. There will be no change to the Form, Fit, or Function of products affected unless specifically indicated.

• Affected Product Type:

Table 1:

Function: Small Signal Switching Diodes				
BAV99	BAV70	MMBD7000		

Table 2:

Function: Bipolar Junction Transistors				
MMBT3904	MMBT3906	MMBT2907A		

•	Effective Date: 28" J	une, 2023		

The reliability test results are summarized below:

Product reliability test result: PASS

No.	DESCRIPTION	TEST CONDITION	DURATION FAILURE RA		E RATE
1	Temperature Cycling (TCT)	Ta = -55°C ~ +150°C (2 cycles / Hour)	1000 CYCLES	0/77 PCS	3 LOTS PASS
2	High Temperature Storage Test (HTSL)	Ta = 150°C	1000 HOURS	0/77 PCS	3 LOTS PASS
3	Resistance to Solder Heat (RSH)	Temperature of solder pot = 260 ±5°C Time for dipping in solder = 10 +2/-0 Sec	1 CYCLE	0/30 PCS	3 LOTS PASS
4	Solder ability (SD)	Temperature of solder pot = 245 ±5°C Time for dipping in solder = 5 ±0.5 Sec	1 CYCLE	0/10 PCS	3 LOTS PASS
5	Intermittent Forward Operation Life (IFOL)	△Tj≧100°C Power On: 120 sec Power Off: 120 sec	15000 CYCLES	0/77 PCS	3 LOTS PASS
6	High Temperature Reverse Bias (HTRB)	Ta = 140°C , VR = 80%VB, DC supply	1000 HOURS	0/77 PCS	3 LOTS PASS
7	Autoclave (AC)	Ta = 121°C, P = 29.7psia ,100%RH	96 HOURS	0/77 PCS	3 LOTS PASS
8	Temperature Humidity Storage (THS)	Ta = 85°C , RH = 85%	1000 HOURS	0/77 PCS	3 LOTS PASS

• ELECTRICAL CHARACTERISTICS SUMMARY:

There is no change to the product electrical specifications.

SAMPLES NEED :

Contact your local PANJIT sales representative.

• TECHNICAL CONTACT:

E-mail: alanliu@panjit.com.tw

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local PANJIT sales representative.

ADDITIONAL RELIABILITY:

Contact your local PANJIT sales representative.

CHANGED PART IDENTIFICATION :

The tracking of 1st delivery after change can be identified by production lot number. Please contact your local sales for tracking lot number.

Please refer to below Lot number rule:

Lot number: 2924XXXXX.

1st digit "2" denotes Year 2022. 2nd digit "9" denotes September. 3rd and 4th digits denote Day.

From 5th digits (XXXXX) denotes production serial number.

Customer Acknowledgement Form

(To be filled out by the cus	tomer and returned to HQBU of PA	ANJIT)
The indicated Customer Notification letter authority.	was received and acknowledged b	y the undersigned
Company Name :	_	
Customer Name :	_(Signature) Date :	
PCN Number: PCN#2303003		
Approval for the Product/Process change:	□Yes □No	
Comments/Additional requests:		
Thanks for your attention on this matter. P	lease return the acknowledgment	form to your local

Please note that no objection within 30 days upon receiving will be deemed as being accepted and agreed with this Process Change Notification.